



Material Content Data Sheet



Sales Product Name		BFP 460 H6327		Issued		19. July 2018		
MA#		MA001309748						
Package		PG-SOT343-4-1		Weight*		6.74 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.002	0.03		268	
	non noble metal	tin	7440-31-5	0.000	0.01		69	
	inorganic material	silicon	7440-21-3	0.016	0.23	0.27	2312	2649
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		100	
	non noble metal	titanium	7440-32-6	0.003	0.05		499	
	non noble metal	chromium	7440-47-3	0.010	0.15		1497	
	non noble metal	copper	7440-50-8	3.347	49.69	49.90	496967	499063
wire	noble metal	gold	7440-57-5	0.013	0.19	0.19	1911	1911
encapsulation	organic material	carbon black	1333-86-4	0.031	0.46		4573	
	plastics	epoxy resin	-	0.662	9.83		98322	
	inorganic material	silicondioxide	60676-86-0	2.387	35.44	45.73	354418	457313
leadfinish	non noble metal	tin	7440-31-5	0.199	2.96	2.96	29580	29580
plating	noble metal	silver	7440-22-4	0.064	0.95	0.95	9484	9484
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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